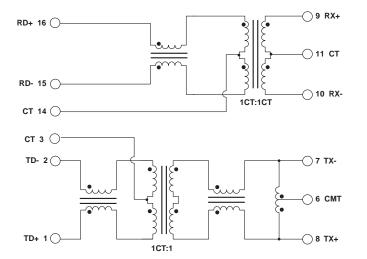
HIGH SPEED LAN MAGNETICS MODULES Designed for 10/100Base-TX

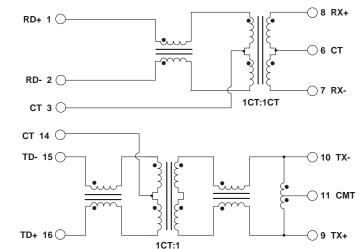


Schematics (continued)

PE-68517, PE-68517L, H1019

H1042



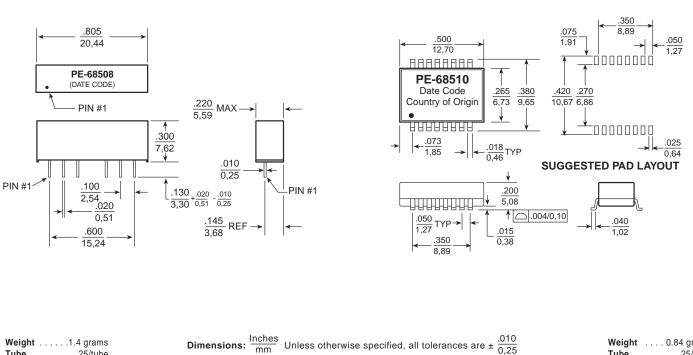


NOTE: Pins 5 and 12 are "No Connect." Connect pins 3 and 14 to analog GND for added shielding.

Mechanicals



PE-68510



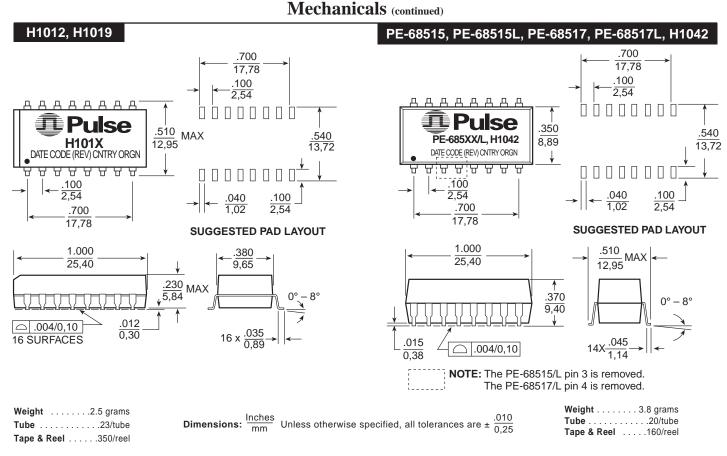
Weight 0.84 grams Tape & Reel900/reel

12220 WORLD TRADE DRIVE, SAN DIEGO, CALIFORNIA 92128 • TEL 619-674-8100 • FAX 619-674-8262 • http://www.pulseeng.com H303.D (4/97)

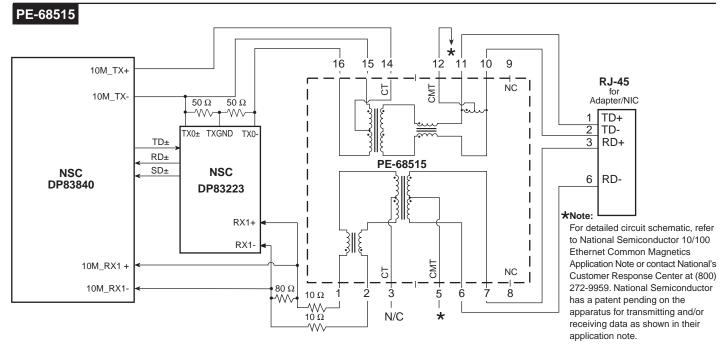
Downloaded from Arrow.com.

HIGH SPEED LAN MAGNETICS MODULES Designed for 10/100Base-TX





Typical Application Circuits and Schematics



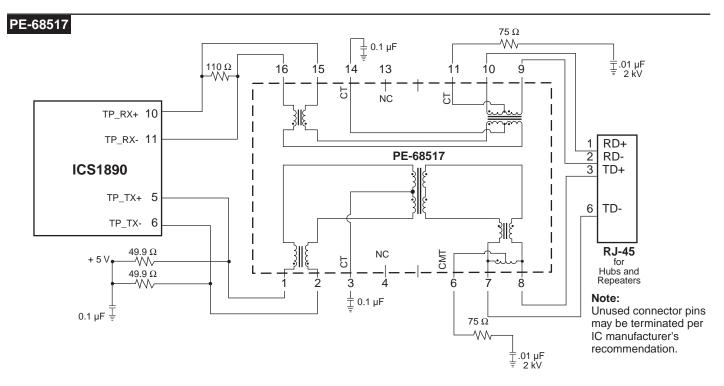
12220 WORLD TRADE DRIVE, SAN DIEGO, CALIFORNIA 92128 • TEL 619-674-8100 • FAX 619-674-8262 • http://www.pulseeng.com

H303.D (4/97)

HIGH SPEED LAN MAGNETICS MODULES Designed for 10/100Base-TX



Typical Application Circuits and Schematics (continued)



Application Notes

This line of 10/100Base-TX magnetics modules have been specifically designed for the implementation of a 10Base-T and 100Base-TX transmission over data grade unshielded twisted pair cable (UTP-5). The modules provide excellent EMI filtering and are suitable for adapter card and multiport applications. The accessibility of the primary center-tap of the transmit isolation transformer allows for impedance matching of both the 10Base-T and 100Base-TX signals. This allows the system designer to provide a single magnetics module and RJ-45 connector solution for both data rates.

Pulse has worked closely with the leading IC manufacturers in providing these 10/100 solutions. This assures compatibility with each transceiver. Additionally, each of the single channel (TX & RX included) solutions meet the stringent open circuit inductance requirements imposed by the IEEE. When an 8 mA DC current is applied across the transformer windings, the transformer will provide at least 350 μ H over the full operating temperature range ($0C^{\circ}$ to $70^{\circ}C$). The transformers used in each module also provide 1500 Vrms minimum isolation, wide bandwidth with minimal attenuation and fast rise times to minimize system level jitter.

Surface mount devices manufactured by Pulse are designed to meet all published specifications after exposure to surface mount soldering temperatures. The SMT modules in this data sheet are transfer molded in I.C. style packaging, making them robust enough to withstand convection and infrared reflow solder temperatures of up to 235°C. Additionally, compliant leads provide excellent solder-joint reliability with a coplanarity of $\pm.002"$ (0,05 mm).

NOTE: Modules are packaged in tubes, unless Tape & Reel is specified. Please add the suffix "**T**", such as H1012**T** for Tape & Reel orders.

For More Information :

Corporate	Europe	Asia	Distributor
12220 World Trade Drive	Millpool House	P.O. Box 26-11, KEPZ	
San Diego, CA 92128	Mill Lane, Godalming	6 Central Sixth Road	
Tel: 619 674 8100	Surrey GU7 1EY	KEPZ, Kaohsiung	
FAX: 619 674 8262	U.K.	Taiwan, R.O.C.	
http://www.pulseeng.com	Tel: 441 483 428 877	Tel: 886 7 821 3141	
Quick-Facts: 619 674 9672	FAX: 441 483 416 011	FAX: 886 7 841 9707	

Performance warranty of products offered on this data sheet is limited to the parameters specified. Data is subject to change without notice. Other brand and product names mentioned herein may be trademarks or registered trademarks of their respective owners.

Printed on recycled paper. ©1997, Pulse Engineering, Inc.